

## High temperature Transil™ for automotive applications

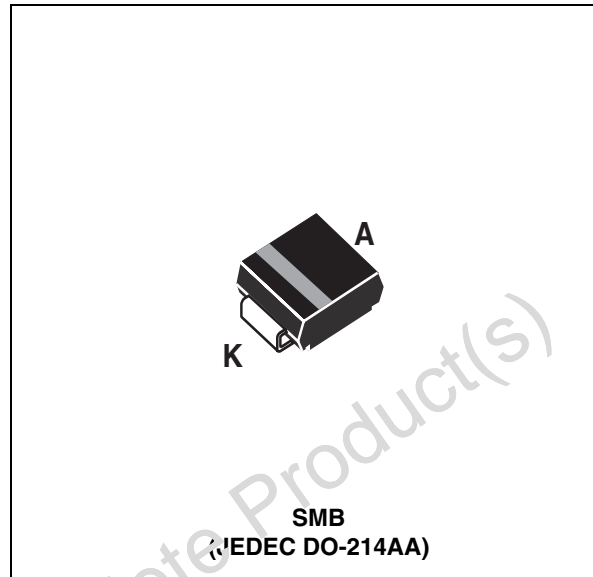
### Features

- High performance TRANSIL designed to fit high temperature environment like automotive applications
- High reliability planar technology
- High performance in voltage regulation mode
- Very low leakage current:
  - $I_R \text{ max.} = 5 \mu\text{A} @ T_{\text{amb}} = 150^\circ \text{C}$
- Peak pulse power: 600 W (10/1000  $\mu\text{s}$ )
- Fast response time
- Unidirectional type
- Low clamping factor

### Description

This high performance Transil series has been designed to fit high temperature environment such as automotive applications, using surface mount technology.

These devices are using high reliability planar technology resulting in high performances in voltage regulation mode and low leakage current at high temperature.



### Order codes

Part number	Marking
SM6HT24A	EMB
SM6HT27A	EPB
SM6HT30A	ERB
SM6HT36A	EVB
SM6HT39A	EXB
SM6HT43A	EYB

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# 1 Characteristics

**Table 1. Absolute maximum rating (T<sub>amb</sub> = 25° C)**

Symbol	Parameter		Value	Unit
P <sub>PP</sub>	Peak pulse power dissipation <sup>(1)</sup>	T <sub>j</sub> initial = T <sub>amb</sub>	600	W
P	Power dissipation on infinite heatsink	T <sub>amb</sub> = 50° C	6	W
I <sub>FSM</sub>	Non repetitive surge peak forward current for unidirectional types	t <sub>p</sub> = 10 ms T <sub>j</sub> initial = T <sub>amb</sub>	75	A
T <sub>stg</sub> / T <sub>j</sub>	Storage and operating junction temperature range		-65 to 175	°C
T <sub>L</sub>	Maximum lead temperature for soldering during 10 s.		260	°C

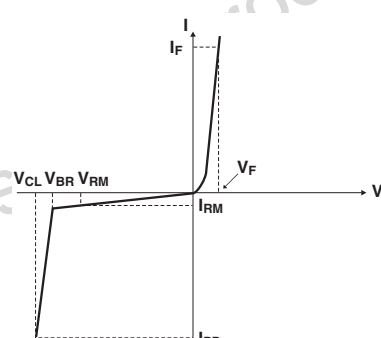
1. for a surge greater than the maximum values, the diode will fail in short circuit.

**Table 2. Thermal resistances**

Symbol	Parameter	Value	Unit
R <sub>th(j-l)</sub>	Junction to leads	20	°C/W
R <sub>th(j-a)</sub>	Junction to ambient on printed circuit on recommended pad layout	100	°C/W

**Table 3. Electrical characteristics (T<sub>amb</sub> = 25° C)**

Symbol	Parameter
V <sub>RM</sub>	Stand-off voltage
V <sub>BR</sub>	Breakdown voltage
V <sub>CL</sub>	Clamping voltage
I <sub>RM</sub>	Leakage current
I <sub>PP</sub>	Peak pulse current
V <sub>F</sub>	Forward voltage drop V <sub>F</sub> < 3.5 V @ I <sub>F</sub> = 50 A (pulse test: t <sub>p</sub> ≤ 500 μs)
I <sub>Z</sub>	Continuous regulation current



The graph shows the diode's current-voltage characteristics. The x-axis is voltage (V) and the y-axis is current (I). Key points are marked: V<sub>CL</sub> (clamping voltage), V<sub>BR</sub> (breakdown voltage), V<sub>RM</sub> (stand-off voltage), V<sub>F</sub> (forward voltage drop), I<sub>RM</sub> (leakage current), and I<sub>PP</sub> (peak pulse current).

Types	Marking	I <sub>RM</sub> @ V <sub>BR</sub>		V <sub>BR</sub> @ I <sub>R</sub> <sup>(1)</sup>				V <sub>CL</sub> @ I <sub>PP</sub>		αT <sup>(2)</sup>	I <sub>Z</sub> @ T <sub>amb</sub> =50°C	
		T <sub>amb</sub> =25° C	T <sub>amb</sub> =150° C				10/1000 μs					
		max	max	min	nom	max	max	max				
SM6HT24A	EMB	2	5	20.5	22.8	24	25.2	1	33.2	18.0	10 <sup>-4</sup> /°C	50
SM6HT27A	EPB			23.1	25.7	27	28.4		37.5	16.0		
SM6HT30A	ERB			25.6	28.5	30	31.5		41.5	14.5		
SM6HT36A	EVB			30.8	34.2	36	37.8		49.9	12.0		
SM6HT39A	EXB			33.3	37.1	39	41.0		53.9	11.1		
SM6HT43A	EYB			36.8	40.9	43	45.2		59.3	10.1		

1. Pulse test: t<sub>p</sub> < 50 ms

2. ΔV<sub>BR</sub> = αT × (T<sub>amb</sub> - 25) × V<sub>BR</sub> (25° C)

Figure 1. Peak power dissipation versus initial junction temperature

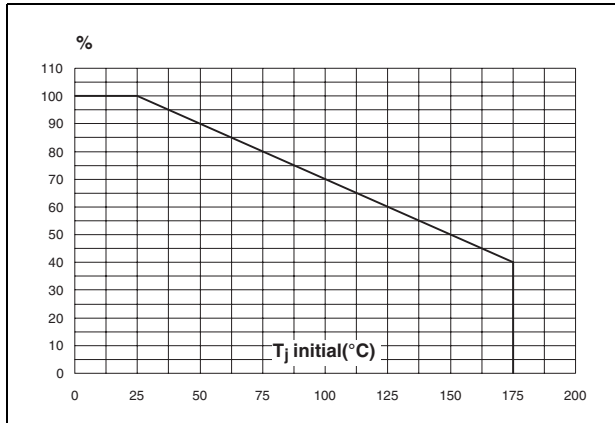


Figure 2. Continuous power dissipation versus ambient temperature

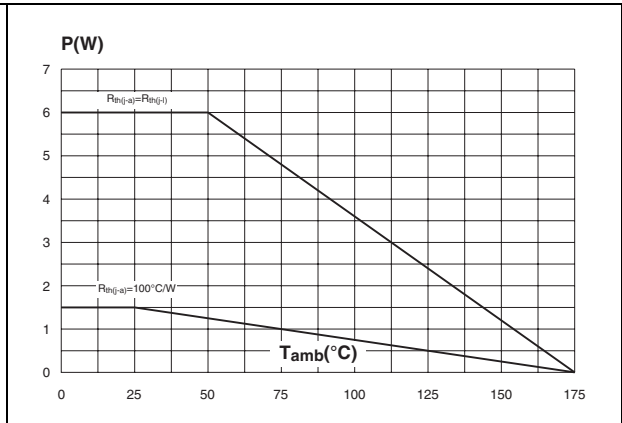


Figure 3. Peak pulse power versus exponential pulse duration (Tj initial = 25°C)

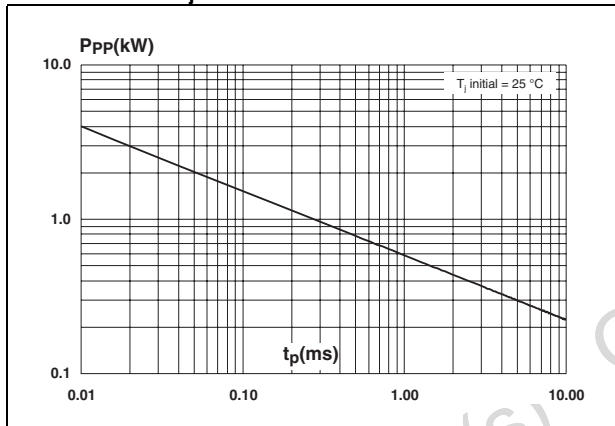


Figure 4. Clamping voltage versus peak pulse current (Tj initial = 25°C)

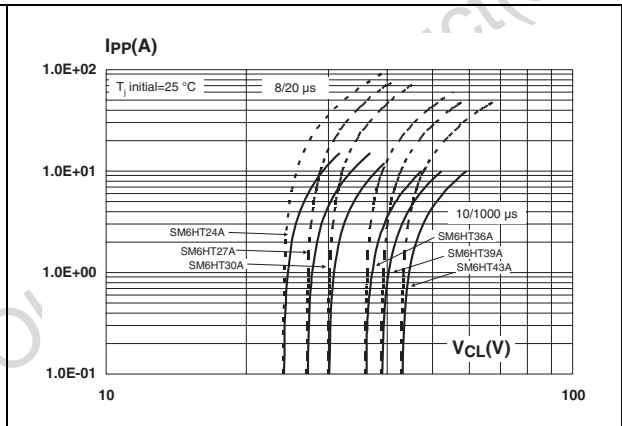


Figure 5. Junction capacitance versus reverse applied voltage (typical values)

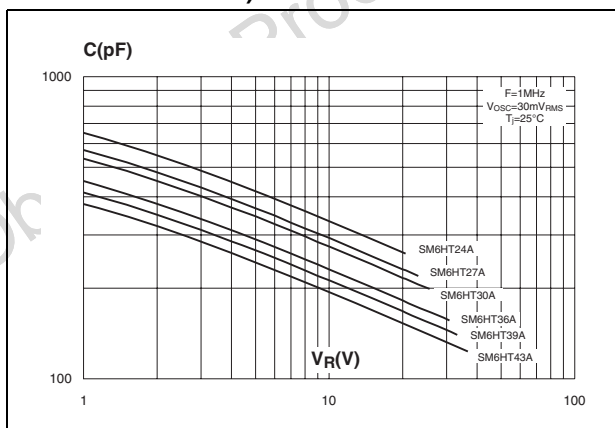
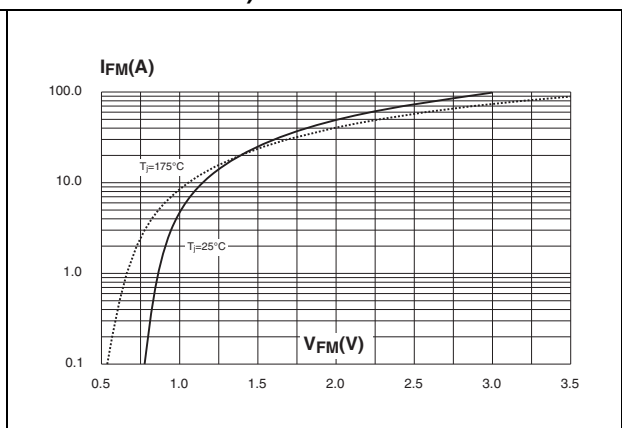
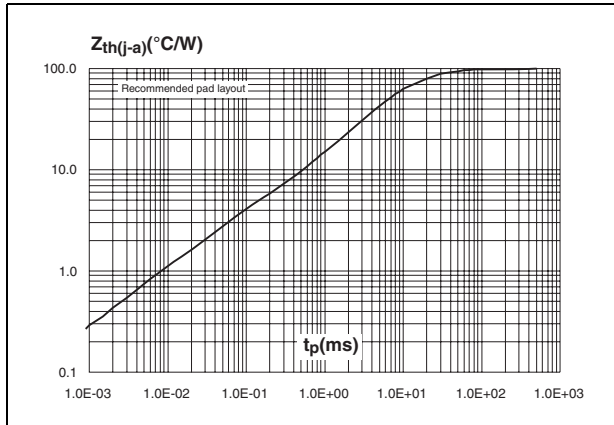


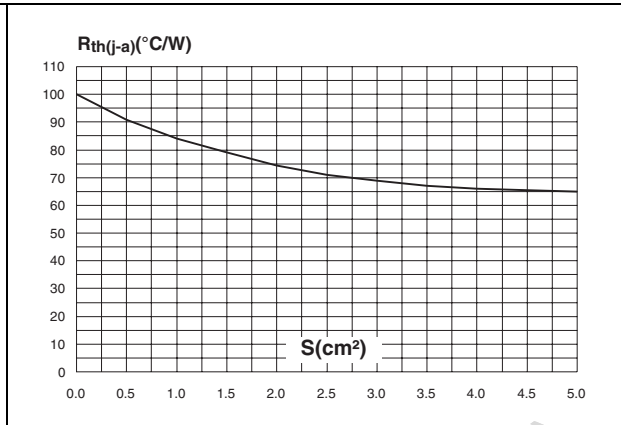
Figure 6. Peak forward voltage drop versus peak forward current (typical values)



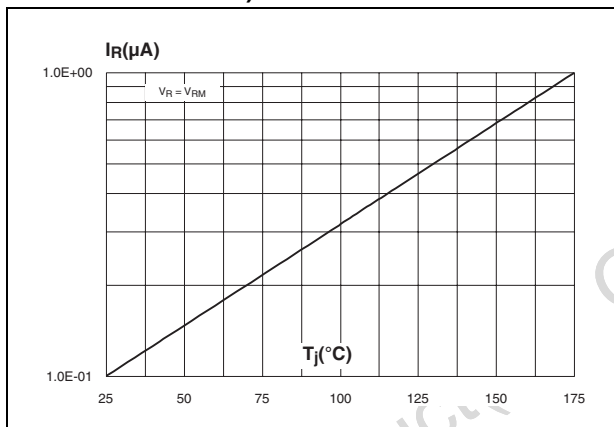
**Figure 7. Variation of thermal impedance junction to ambient versus pulse duration (Printed circuit board FR4 with recommended pad layout)**



**Figure 8. Thermal resistance junction to ambient versus copper surface under each lead (printed circuit board FR4,  $e_{Cu} = 35 \mu m$ )**

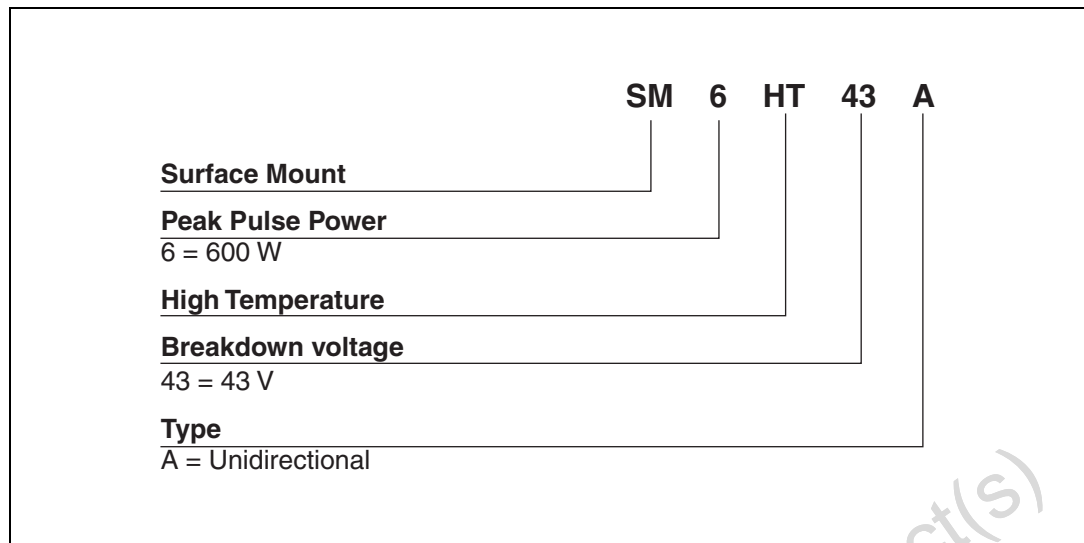


**Figure 9. Variation of leakage current versus junction temperature (typical values)**



Obsolete Product(s)

## 2 Order information scheme



Obsolete Product(s) - Obsolete Product(s)

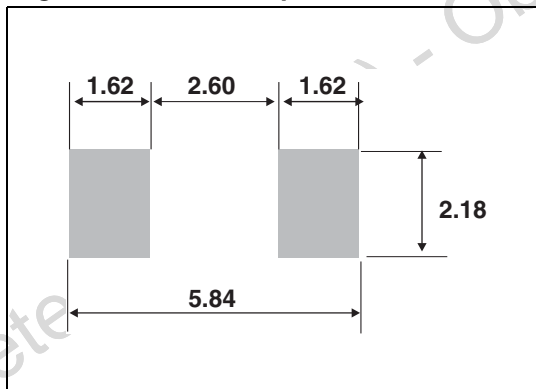
### 3 Package information

- Case: JEDEC DO-214AA molded plastic over Planar junction
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: For unidirectional types the band indicates cathode.
- Flammability: Epoxy is rated UL94V-0
- RoHS package

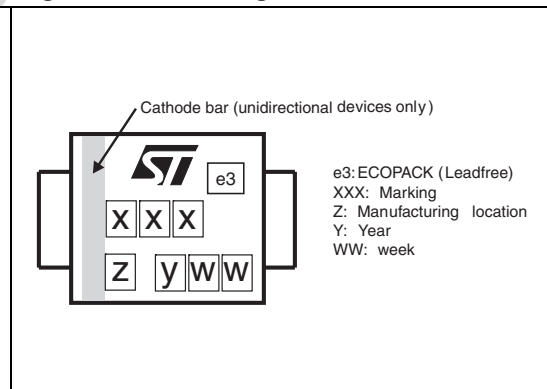
**Table 4. SMB dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.50	0.030	0.059

**Figure 10. SMB footprint dimensions**



**Figure 11. Marking information**



## 4 Ordering information

Part number	Marking	Package	Weight	Base qty	Delivery mode
SM6HT24A	EMB	SMB	0.12 g	5000	Tape and reel
SM6HT27A	EPB				
SM6HT30A	ERB				
SM6HT36A	EVB				
SM6HT39A	EXB				
SM6HT43A	EYB				

## 5 Revision history

Date	Revision	Changes
Apr-1999	4A	Last release.
26-Jan-2005	5	Figure 9 on page 4: leakage current improved.
18-Mar-2005	6	Table 3: Electrical characteristics ( $T_{amb} = 25^{\circ}C$ ) on page 2: $V_F$ specification added.
21-Mar-2007	7	<a href="#">Table 1 on page 2</a> : Power dissipation upgraded from 5 W to 6 W. <a href="#">Table 3 on page 2</a> : $I_Z$ max parameter added. <a href="#">Figure 2 on page 3</a> : Updated for 6 W power dissipation.

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